

To: Technology Unit: 2814
Facsimile Number: 703-872-9306

Total Pages Sent 5

From: W. Daniel Swayze, Jr.
Texas Instruments Incorporated
Facsimile: 972-917-4418
Phone: 972-917-5633

RECEIVED
CENTRAL FAX CENTER
OCT 21 2004

FACSIMILE COVER SHEET

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at 703-872-9306 on the date shown below:

Tommie Chambers 10-21-04
Tommie Chambers Date

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET	<input checked="" type="checkbox"/> AMENDMENT 116 (4 Pages)
<input type="checkbox"/> NEW APPLICATION	<input type="checkbox"/> EOT (# Month)
<input type="checkbox"/> DECLARATION (# Pages)	<input type="checkbox"/> NOTICE OF APPEAL
<input type="checkbox"/> ASSIGNMENT (# Pages)	<input type="checkbox"/> APPEAL (# Pages)
<input type="checkbox"/> FORMAL DRAWINGS	<input type="checkbox"/> ISSUE FEE (# Pages)
<input type="checkbox"/> INFORMAL DRAWINGS	<input type="checkbox"/> PETITION TO REVIVE
<input type="checkbox"/> CONTINUATION APP'N (# Pages)	
<input type="checkbox"/> DIVISIONAL APP'N	
NAME OF INVENTOR(S): Yew	
RECEIPT DATE & SERIAL NO.: Serial No.: 10/612,129 Filing Date: 7/2/2003	
TITLE OF INVENTION: DIRECT ATTACHMENT OF SEMICONDUCTOR CHIP TO ORGANIC SUBSTRATE	
TI FILE NO.: TI-26239.1	DEPOSIT ACCT. NO.: 20-0668
FAXED: 10/21/2004 DUE: 10/06/2004 ATTY/SEC'Y: WDS/ltc	

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265

RECEIVED
CENTRAL FAX CENTER
OCT 21 2004

RESIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Yew
Serial No: 10/612,129
Filed: 7/2/2003
For: DIRECT ATTACHMENT OF SEMICONDUCTOR CHIP TO ORGANIC
SUBSTRATE

Docket No: TI-26239.1
Examiner: Cao, Phat X.
Art Unit: 2814

RESPONSE UNDER 37 C.F.R. § 1.116

Assistant Commissioner For Patents
Washington, DC 20231

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being
transmitted by facsimile to the U.S. Patent and Trademark
Office at 703-872-9306 on 10-21-04:

Tommy Chambers
Tommy Chambers

Dear Sir:

Responsive to the Office Action mailed August 6, 2004 in connection with the
above identified application, Applicants respectfully submit the following remarks.